

74HC273-Q100; 74HCT273-Q100

Octal D-type flip-flop with reset; positive-edge trigger

Rev. 3 — 5 August 2024

Product data sheet

1. General description

The 74HC273-Q100; 74HCT273-Q100 is an octal positive-edge triggered D-type flip-flop. The device features clock (CP) and master reset ($\overline{\text{MR}}$) inputs. The outputs Q_n will assume the state of their corresponding D_n inputs that meet the set-up and hold time requirements on the LOW-to-HIGH clock (CP) transition. A LOW on $\overline{\text{MR}}$ forces the outputs LOW independently of clock and data inputs. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC} .

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

2. Features and benefits

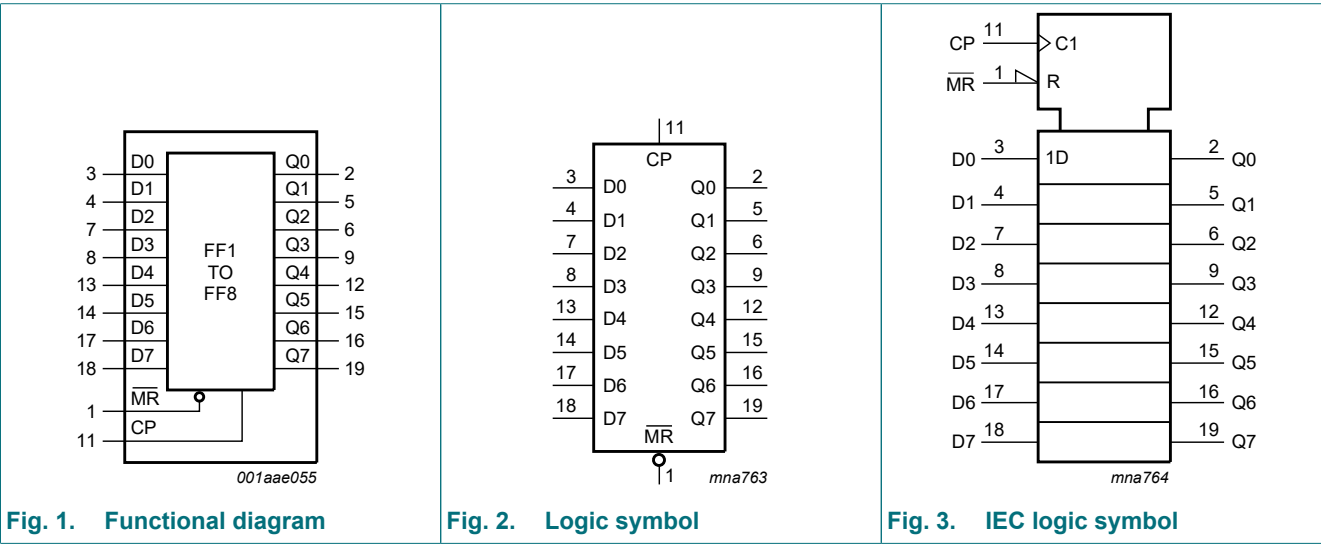
- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
 - Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$
- Wide supply voltage range from 2.0 V to 6.0 V
- CMOS low power dissipation
- High noise immunity
- Latch-up performance exceeds 100 mA per JESD 78 Class II Level B
- Complies with JEDEC standards:
 - JESD8C (2.7 V to 3.6 V)
 - JESD7A (2.0 V to 6.0 V)
- Input levels:
 - For 74HC273-Q100: CMOS level
 - For 74HCT273-Q100: TTL level
- Common clock and master reset
- Eight positive edge-triggered D-type flip-flops
- ESD protection:
 - HBM: ANSI/ESDA/JEDEC JS-001 class 2 exceeds 2000 V
 - CDM: ANSI/ESDA/JEDEC JS-002 class C3 exceeds 1000 V
- Multiple package options
- DHVQFN package with Side-Wettable Flanks enabling Automated Optical Inspection (AOI) of solder joints

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC273D-Q100 74HCT273D-Q100	-40 °C to +125 °C	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
74HC273PW-Q100 74HCT273PW-Q100	-40 °C to +125 °C	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1
74HC273BQ-Q100 74HCT273BQ-Q100	-40 °C to +125 °C	DHVQFN20	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 20 terminals; body 2.5 × 4.5 × 0.85 mm	SOT764-1

4. Functional diagram



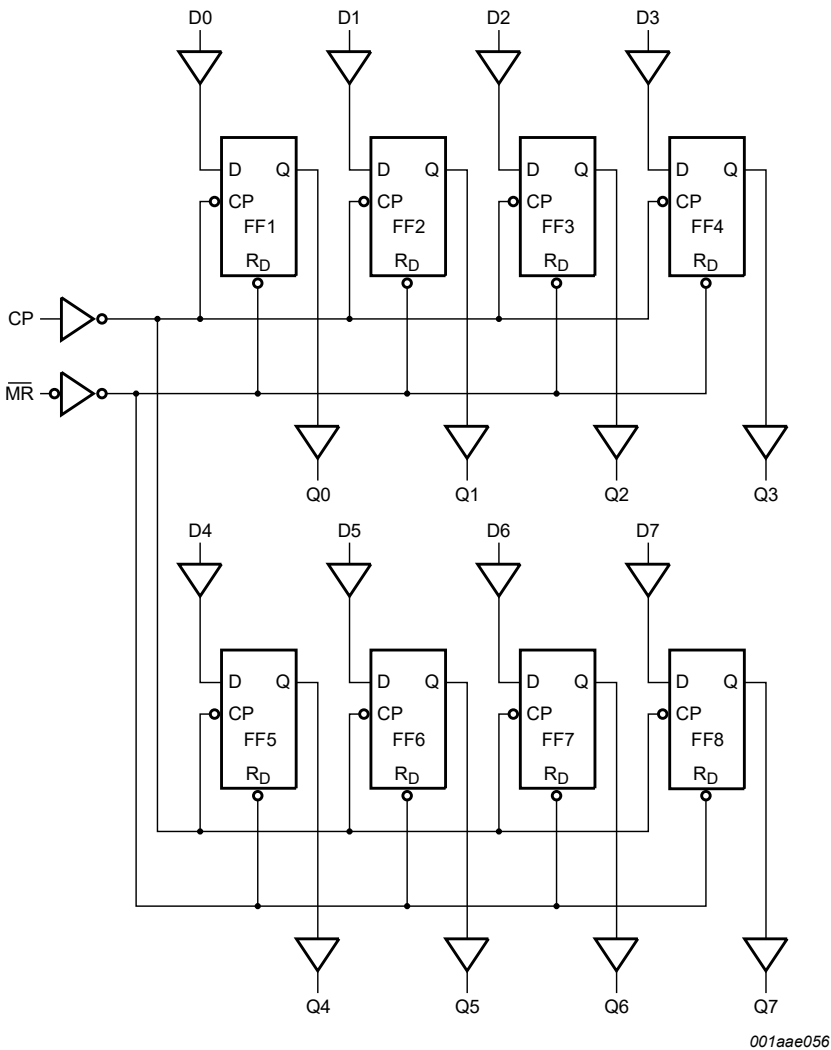


Fig. 4. Logic diagram

5. Pinning information

5.1. Pinning

D package
SOT163-1 (SO20)

aaa-035046

PW package
SOT360-1 (TSSOP20)

aaa-035047

BQ package
SOT764-1 (DHVQFN20)

terminal 1
index area

GND(1)

aaa-035048

Transparent top view

(1) This is not a ground pin. There is no electrical or mechanical requirement to solder the pad. In case soldered, the solder land should remain floating or connected to GND.

5.2. Pin description

Table 2. Pin description

Symbol	Pin	Description
MR	1	master reset input (active LOW)
Q0, Q1, Q2, Q3, Q4, Q5, Q6, Q7	2, 5, 6, 9, 12, 15, 16, 19	flip-flop output
D0, D1, D2, D3, D4, D5, D6, D7	3, 4, 7, 8, 13, 14, 17, 18	data input
GND	10	ground (0 V)
CP	11	clock input (LOW-to-HIGH, edge-triggered)
V _{CC}	20	supply voltage

6. Functional description

Table 3. Function table

H = HIGH voltage level; h = HIGH voltage level one set-up time prior to the LOW-to-HIGH clock transition;
L = LOW voltage level; l = LOW voltage level one set-up time prior to the LOW-to-HIGH clock transition;
X = don't care; ↑ = LOW-to-HIGH clock transition.

Operating modes	Inputs			Outputs
	MR	CP	Dn	Qn
reset (clear)	L	X	X	L
load "1"	H	↑	h	H
load "0"	H	↑	l	L

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		-0.5	+7	V
I _{IK}	input clamping current	V _I < -0.5 V or V _I > V _{CC} + 0.5 V [1]	-	±20	mA
I _{OK}	output clamping current	V _O < -0.5 V or V _O > V _{CC} + 0.5 V [1]	-	±20	mA
I _O	output current	-0.5 V < V _O < V _{CC} + 0.5 V	-	±25	mA
I _{CC}	supply current		-	50	mA
I _{GND}	ground current		-50	-	mA
T _{stg}	storage temperature		-65	+150	°C
P _{tot}	total power dissipation	T _{amb} = -40 °C to +125 °C [2]	-	500	mW

- [1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
[2] For SOT163-1 (SO20) package: P_{tot} derates linearly with 12.3 mW/K above 109 °C.
For SOT360-1 (TSSOP20) package: P_{tot} derates linearly with 10.0 mW/K above 100 °C.
For SOT764-1 (DHVQFN20) package: P_{tot} derates linearly with 12.9 mW/K above 111 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	74HC273-Q100			74HCT273-Q100			Unit
			Min	Typ	Max	Min	Typ	Max	
V _{CC}	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
V _I	input voltage		0	-	V _{CC}	0	-	V _{CC}	V
V _O	output voltage		0	-	V _{CC}	0	-	V _{CC}	V
T _{amb}	ambient temperature		-40	-	+125	-40	-	+125	°C
Δt/ΔV	input transition rise and fall rate	V _{CC} = 2.0 V	-	-	625	-	-	-	ns/V
		V _{CC} = 4.5 V	-	1.67	139	-	1.67	139	ns/V
		V _{CC} = 6.0 V	-	-	83	-	-	-	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HC273-Q100										
V _{IH}	HIGH-level input voltage	V _{CC} = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
		V _{CC} = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V _{CC} = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V _{CC} = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V _{CC} = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}								
		I _O = -20 µA; V _{CC} = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I _O = -20 µA; V _{CC} = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I _O = -20 µA; V _{CC} = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I _O = -4.0 mA; V _{CC} = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
		I _O = -5.2 mA; V _{CC} = 6.0 V	5.48	5.81	-	5.34	-	5.2	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL}								
		I _O = 20 µA; V _{CC} = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 20 µA; V _{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 20 µA; V _{CC} = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 4.0 mA; V _{CC} = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		I _O = 5.2 mA; V _{CC} = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
I _I	input leakage current	V _I = V _{CC} or GND; V _{CC} = 6.0 V	-	-	±0.1	-	±1	-	±1	µA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 6.0 V	-	-	8.0	-	80	-	160	µA
C _I	input capacitance		-	3.5	-	-	-	-	-	pF

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HCT273-Q100										
V _{IH}	HIGH-level input voltage	V _{CC} = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V								
		I _O = -20 µA	4.4	4.5	-	4.4	-	4.4	-	V
		I _O = -4.0 mA	3.98	4.32	-	3.84	-	3.7	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V								
		I _O = 20 µA; V _{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 5.2 mA; V _{CC} = 5.5 V	-	0.15	0.26	-	0.33	-	0.4	V
I _I	input leakage current	V _I = V _{CC} or GND; V _{CC} = 5.5 V	-	-	±0.1	-	±1	-	±1	µA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V	-	-	8.0	-	80	-	160	µA
ΔI _{CC}	additional supply current	per input pin; V _I = V _{CC} - 2.1 V; other inputs at V _{CC} or GND; V _{CC} = 4.5 V to 5.5 V								
		M $\overline{R}$ input	-	100	360	-	450	-	490	µA
		CP input	-	175	630	-	787.5	-	857.5	µA
		Dn input	-	15	54	-	67.5	-	73.5	µA
C _I	input capacitance		-	3.5	-	-	-	-	-	pF

10. Dynamic characteristics

Table 7. Dynamic characteristics

GND (ground = 0 V); C_L = 50 pF unless otherwise specified; for test circuit, see Fig. 8

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HC273-Q100										
t _{pd}	propagation delay	CP to Qn; see Fig. 5 [1]								
		V _{CC} = 2.0 V	-	41	150	-	185	-	225	ns
		V _{CC} = 4.5 V	-	15	30	-	37	-	45	ns
		V _{CC} = 5.0 V; C _L = 15 pF	-	15	-	-	-	-	-	ns
		V _{CC} = 6.0 V	-	13	26	-	31	-	38	ns
t _{PHL}	HIGH to LOW propagation delay	MR to Qn; see Fig. 6								
		V _{CC} = 2.0 V	-	44	150	-	185	-	225	ns
		V _{CC} = 4.5 V	-	16	30	-	37	-	45	ns
		V _{CC} = 5.0 V; C _L = 15 pF	-	15	-	-	-	-	-	ns
		V _{CC} = 6.0 V	-	14	26	-	31	-	38	ns

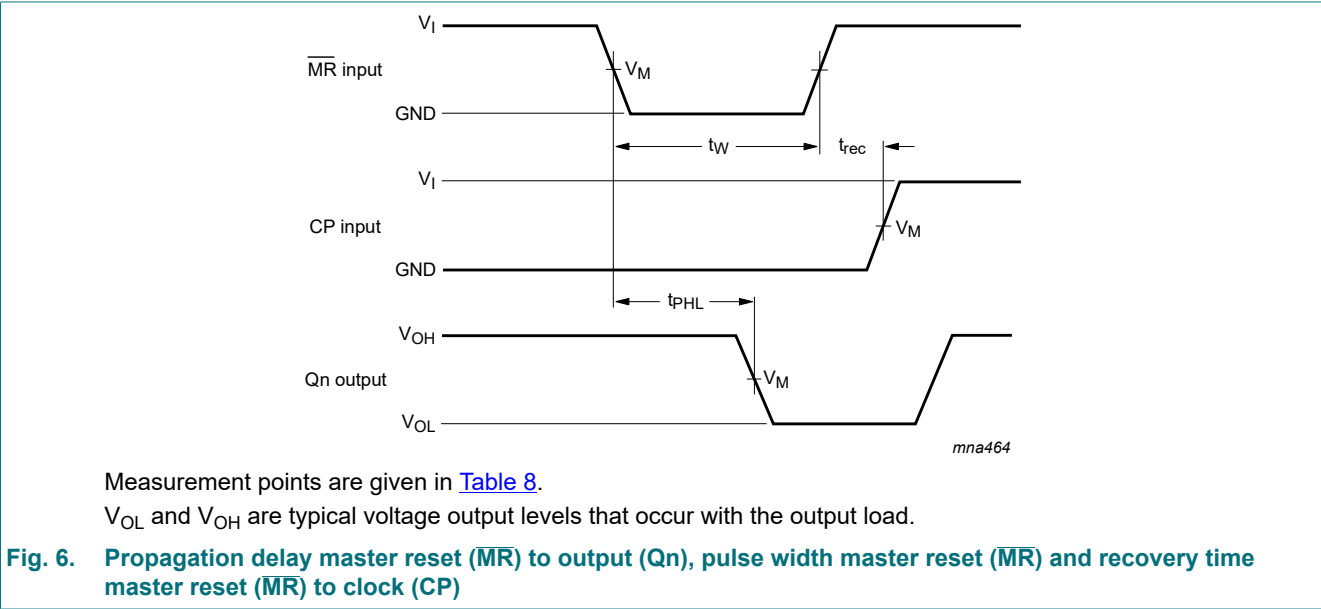
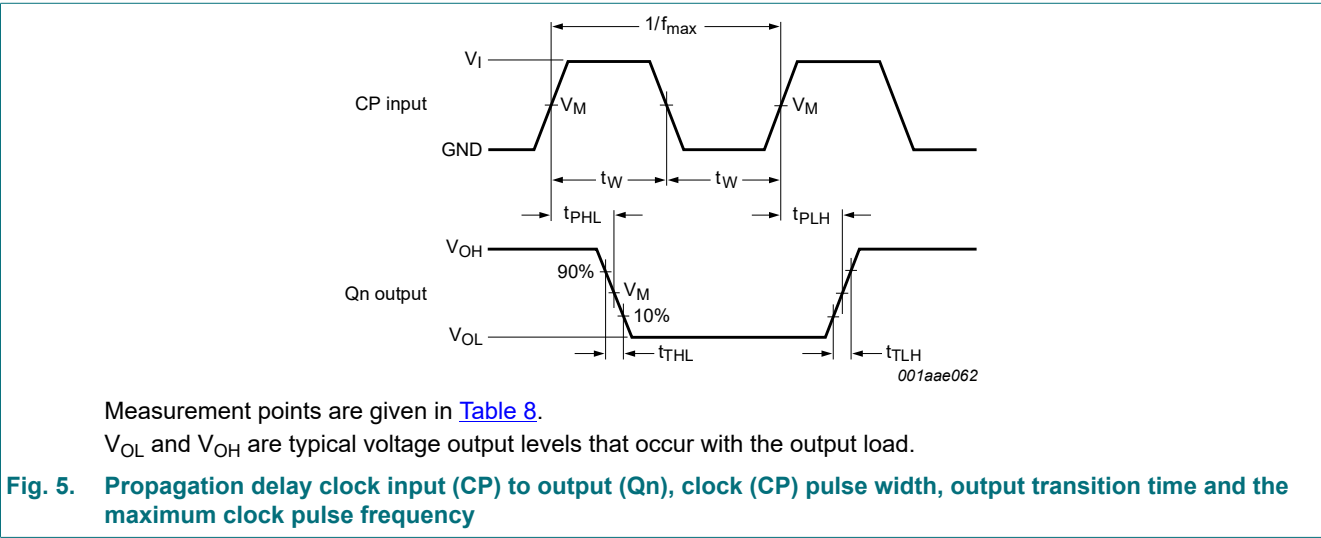
Octal D-type flip-flop with reset; positive-edge trigger

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t _t	transition time	Qn output; see Fig. 5 [2]								
		V _{CC} = 2.0 V	-	19	75	-	95	-	110	ns
		V _{CC} = 4.5 V	-	7	15	-	19	-	22	ns
		V _{CC} = 6.0 V	-	6	13	-	15	-	19	ns
t _W	pulse width	CP input HIGH or LOW; see Fig. 5								
		V _{CC} = 2.0 V	80	14	-	100	-	120	-	ns
		V _{CC} = 4.5 V	16	5	-	20	-	24	-	ns
		V _{CC} = 6.0 V	14	4	-	17	-	20	-	ns
		MR input LOW; see Fig. 6								
		V _{CC} = 2.0 V	60	17	-	75	-	90	-	ns
		V _{CC} = 4.5 V	12	6	-	15	-	18	-	ns
		V _{CC} = 6.0 V	10	5	-	13	-	15	-	ns
t _{rec}	recovery time	MR to CP; see Fig. 6								
		V _{CC} = 2.0 V	50	-6	-	65	-	75	-	ns
		V _{CC} = 4.5 V	10	-2	-	13	-	15	-	ns
		V _{CC} = 6.0 V	9	-2	-	11	-	13	-	ns
t _{su}	set-up time	Dn to CP; see Fig. 7								
		V _{CC} = 2.0 V	60	11	-	75	-	90	-	ns
		V _{CC} = 4.5 V	12	4	-	15	-	18	-	ns
		V _{CC} = 6.0 V	10	3	-	13	-	15	-	ns
t _h	hold time	Dn to CP; see Fig. 7								
		V _{CC} = 2.0 V	3	-6	-	3	-	3	-	ns
		V _{CC} = 4.5 V	3	-2	-	3	-	3	-	ns
		V _{CC} = 6.0 V	3	-2	-	3	-	3	-	ns
f _{max}	maximum frequency	CP input; see Fig. 5								
		V _{CC} = 2.0 V	6	20.6	-	4.8	-	4	-	MHz
		V _{CC} = 4.5 V	30	103	-	24	-	20	-	MHz
		V _{CC} = 5.0 V; C _L = 15 pF	-	66	-	-	-	-	-	MHz
		V _{CC} = 6.0 V	35	122	-	28	-	24	-	MHz
C _{PD}	power dissipation capacitance	per package; V _I = GND to V _{CC} [3]	-	20	-	-	-	-	-	pF

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HCT273-Q100										
t _{pd}	propagation delay	CP to Qn; see Fig. 5 [1]								
		V _{CC} = 4.5 V	-	16	30	-	38	-	45	ns
		V _{CC} = 5.0 V; C _L = 15 pF	-	15	-	-	-	-	-	ns
t _{PHL}	HIGH to LOW propagation delay	MR to Qn; see Fig. 6								
		V _{CC} = 4.5 V	-	23	34	-	43	-	51	ns
		V _{CC} = 5.0 V; C _L = 15 pF	-	20	-	-	-	-	-	ns
t _t	transition time	Qn output; see Fig. 5 [2]								
		V _{CC} = 4.5 V	-	7	15	-	19	-	22	ns
t _W	pulse width	CP input; see Fig. 5								
		V _{CC} = 4.5 V	16	9	-	20	-	24	-	ns
		MR input LOW; see Fig. 6								
		V _{CC} = 4.5 V	16	8	-	20	-	24	-	ns
t _{rec}	recovery time	MR to CP; see Fig. 6								
		V _{CC} = 4.5 V	10	-2	-	13	-	15	-	ns
t _{su}	set-up time	Dn to CP; see Fig. 7								
		V _{CC} = 4.5 V	12	5	-	15	-	18	-	ns
t _h	hold time	Dn to CP; see Fig. 7								
		V _{CC} = 4.5 V	3	-4	-	3	-	3	-	ns
f _{max}	maximum frequency	CP input; see Fig. 5								
		V _{CC} = 4.5 V	30	56	-	24	-	20	-	MHz
		V _{CC} = 5.0 V; C _L = 15 pF	-	36	-	-	-	-	-	MHz
C _{PD}	power dissipation capacitance	per package; V _I = GND to V _{CC} - 1.5 V [3]	-	23	-	-	-	-	-	pF

[1] t_{pd} is the same as t_{PHL} and t_{PLH}.
[2] t_t is the same as t_{THL} and t_{TLH}.
[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
P_D = C_{PD} × V_{CC}² × f_i + Σ (C_L × V_{CC}² × f_o) where:
f_i = input frequency in MHz;
f_o = output frequency in MHz;
Σ (C_L × V_{CC}² × f_o) = sum of outputs;
C_L = output load capacitance in pF;
V_{CC} = supply voltage in V.

10.1. Waveforms and test circuit



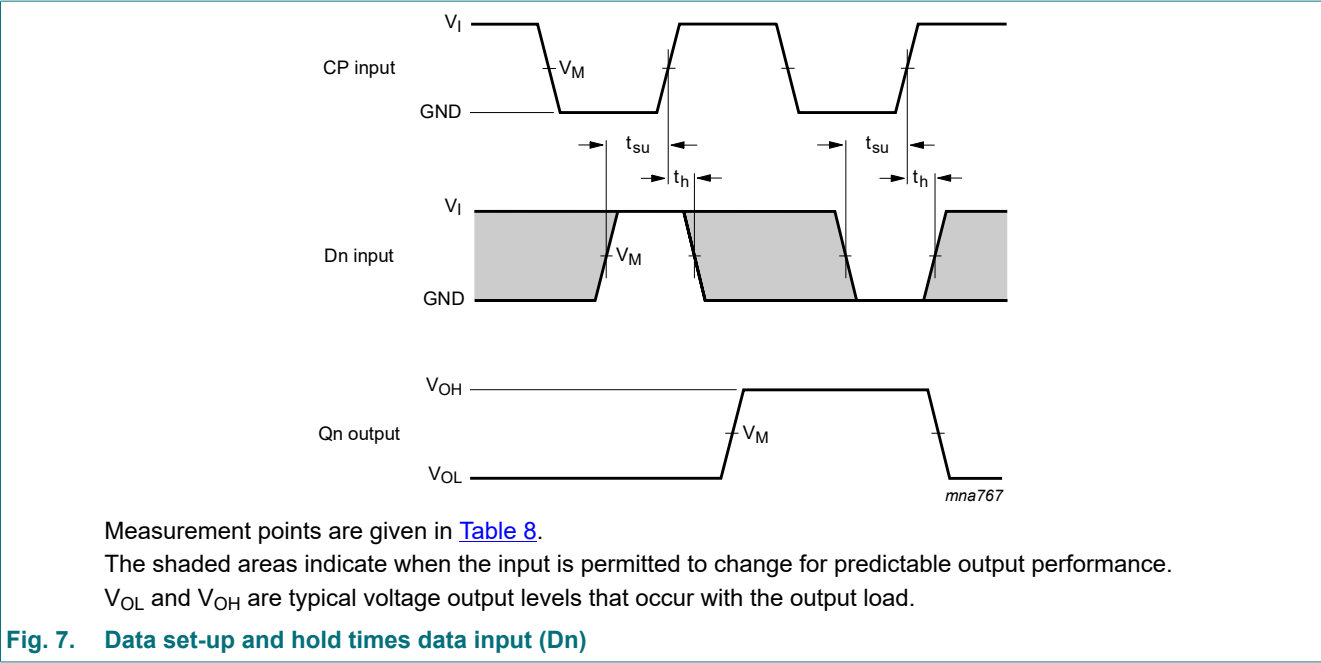


Table 8. Measurement points

Type	Input		Output
	V_I	V_M	V_M
74HC273-Q100	V_{CC}	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
74HCT273-Q100	3 V	1.3 V	1.3 V

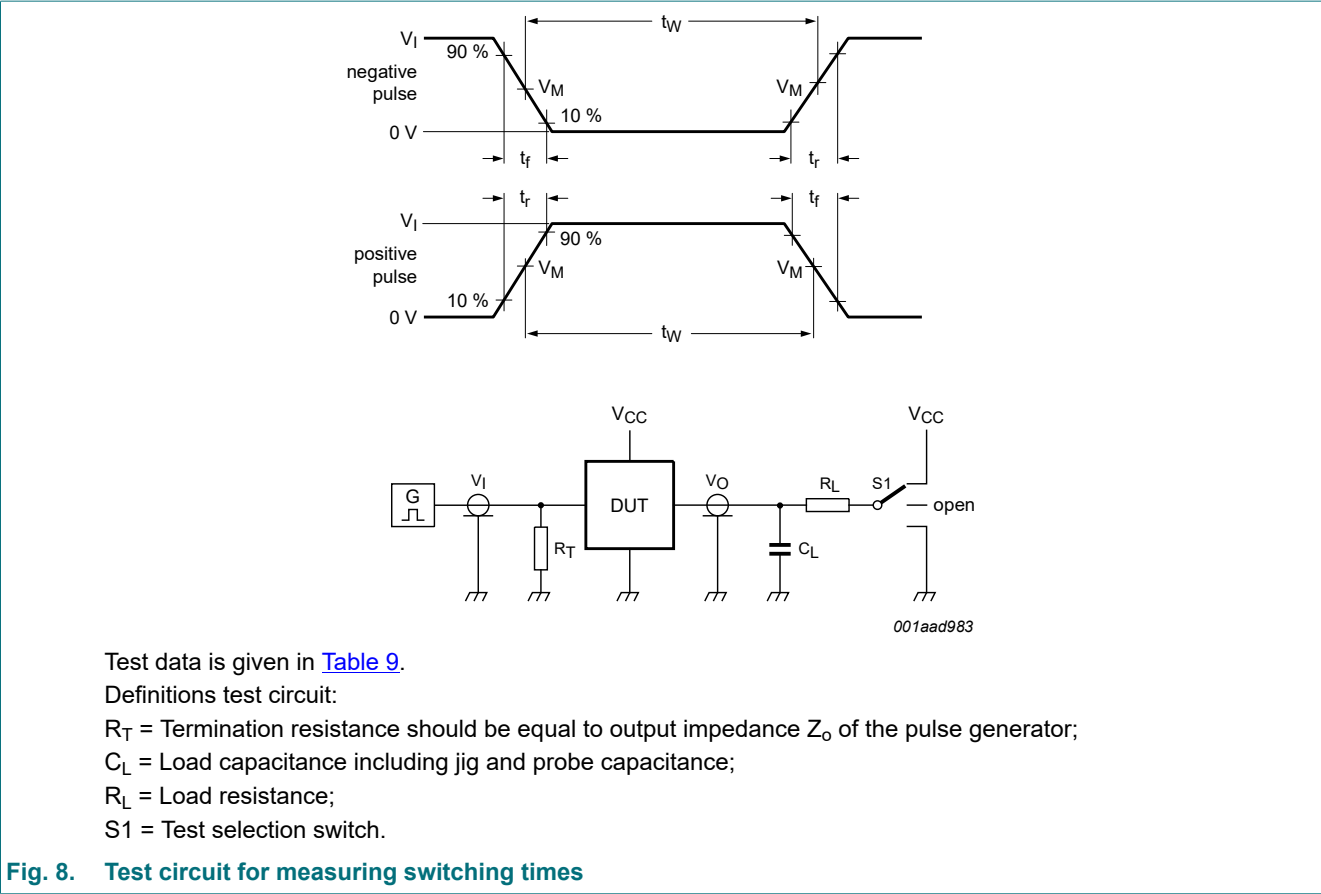


Table 9. Test data

Type	Input		Load		S1 position
	V_I	t_r, t_f	C_L	R_L	
74HC273-Q100	V_{CC}	6 ns	15 pF, 50 pF	1 k Ω	open
74HCT273-Q100	3 V	6 ns	15 pF, 50 pF	1 k Ω	open

11. Package outline

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1

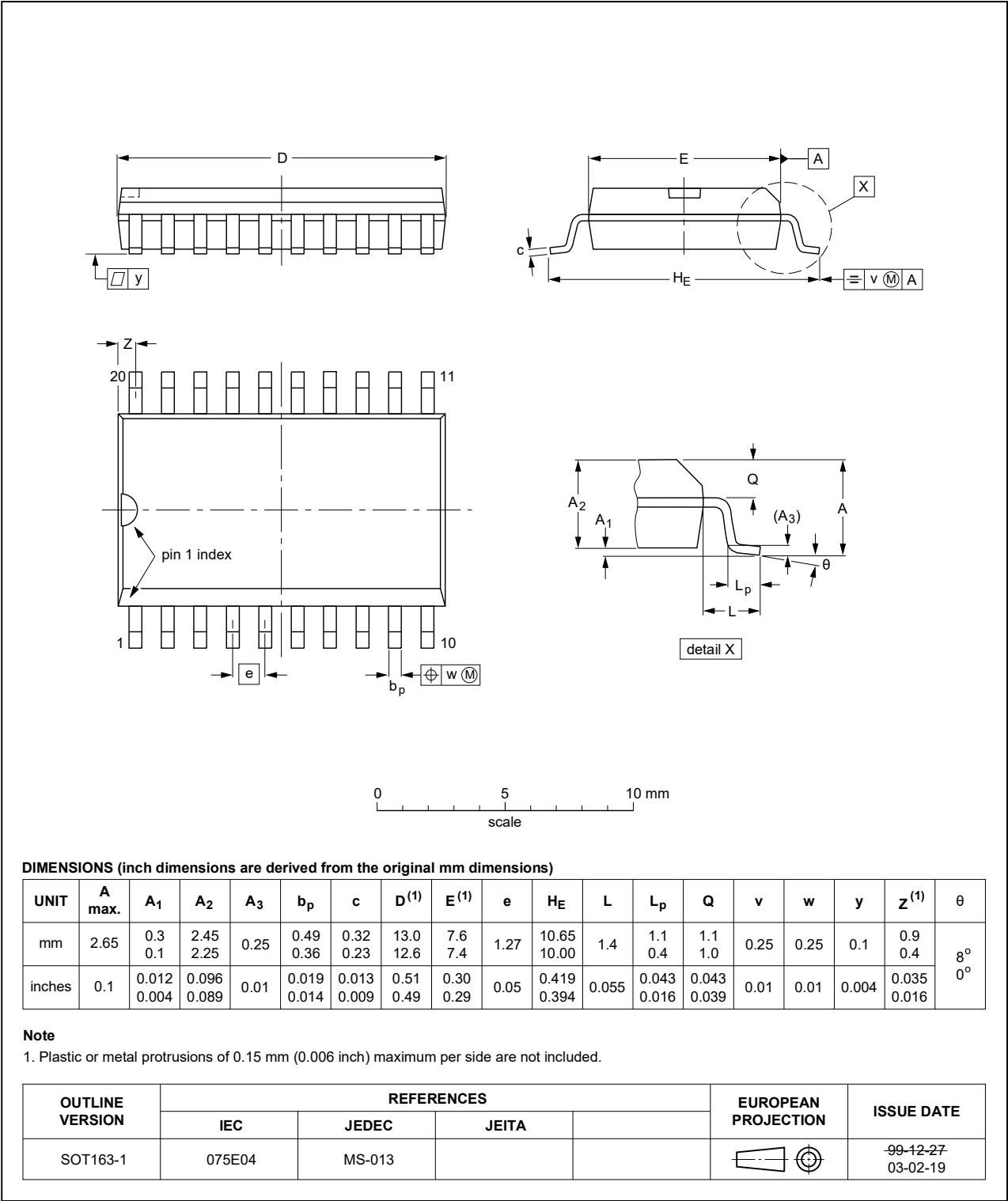


Fig. 9. Package outline SOT163-1 (SO20)

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1

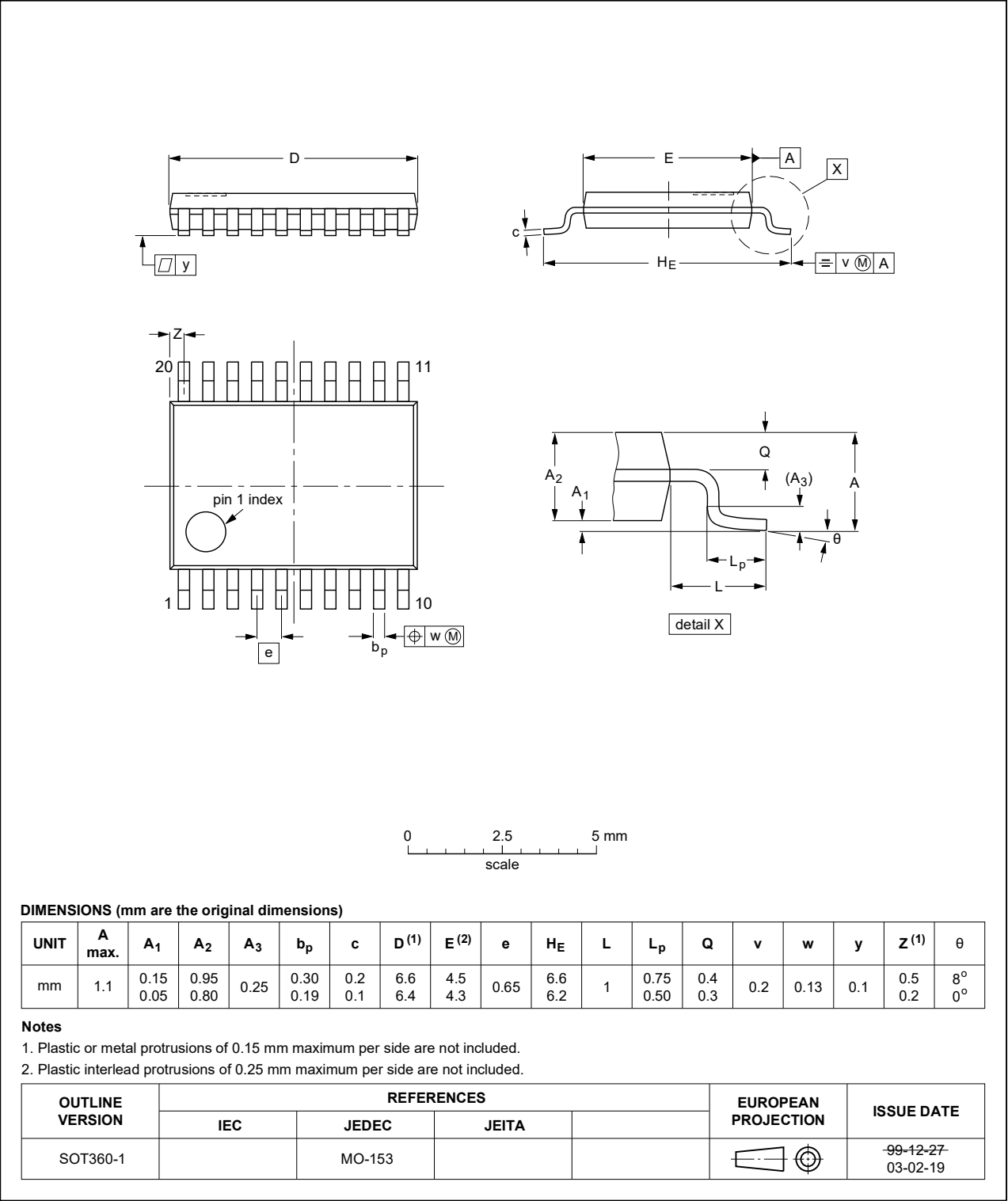


Fig. 10. Package outline SOT360-1 (TSSOP20)

DHVQFN20: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads;
20 terminals; body 2.5 x 4.5 x 0.85 mm

SOT764-1

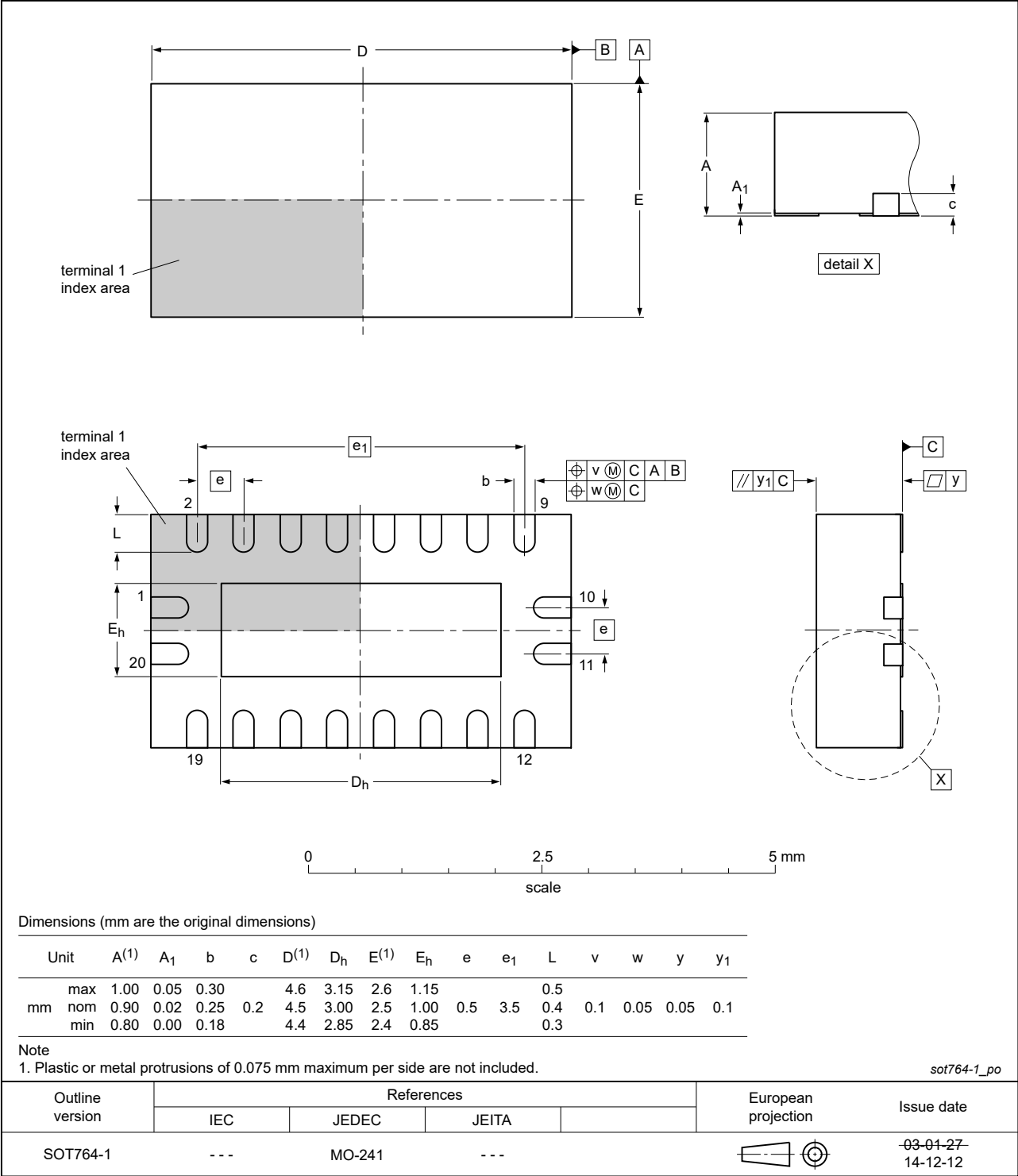


Fig. 11. Package outline SOT764-1 (DHVQFN20)

12. Abbreviations

Table 10. Abbreviations

Acronym	Description
ANSI	American National Standards Institute
CDM	Charged Device Model
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
ESDA	ElectroStatic Discharge Association
HBM	Human Body Model
JEDEC	Joint Electron Device Engineering Council
TTL	Transistor-Transistor Logic

13. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT273_Q100 v.3	20240805	Product data sheet	-	74HC_HCT273_Q100 v.2
Modifications:	• Section 2: ESD specification updated according to the latest JEDEC standard.			
74HC_HCT273_Q100 v.2	20200903	Product data sheet	-	74HC_HCT273_Q100 v.1
Modifications:	• The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia. • Legal texts have been adapted to the new company name where appropriate. • Section 2 updated. • Table 4: Derating values for P_{tot} total power dissipation have been updated. • Package outline drawing of SOT764-1 (Fig. 11) updated.			
74HC_HCT273_Q100 v.1	20130619	Product data sheet	-	-

14. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at <https://www.nexperia.com>.

Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. Nexperia does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local Nexperia sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

Product specification — The information and data provided in a Product data sheet shall define the specification of the product as agreed between Nexperia and its customer, unless Nexperia and customer have explicitly agreed otherwise in writing. In no event however, shall an agreement be valid in which the Nexperia product is deemed to offer functions and qualities beyond those described in the Product data sheet.

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, Nexperia does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. Nexperia takes no responsibility for the content in this document if provided by an information source outside of Nexperia.

In no event shall Nexperia be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, Nexperia's aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of Nexperia.

Right to make changes — Nexperia reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use in automotive applications — This Nexperia product has been qualified for use in automotive applications. Unless otherwise agreed in writing, the product is not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or

equipment, nor in applications where failure or malfunction of an Nexperia product can reasonably be expected to result in personal injury, death or severe property or environmental damage. Nexperia and its suppliers accept no liability for inclusion and/or use of Nexperia products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Quick reference data — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. Nexperia makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using Nexperia products, and Nexperia accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the Nexperia product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

Nexperia does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using Nexperia products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). Nexperia does not accept any liability in this respect.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

Terms and conditions of commercial sale — Nexperia products are sold subject to the general terms and conditions of commercial sale, as published at <http://www.nexperia.com/profile/terms>, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. Nexperia hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of Nexperia products by customer.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

Translations — A non-English (translated) version of a document is for reference only. The English version shall prevail in case of any discrepancy between the translated and English versions.

Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

Contents

1. General description..... 1

2. Features and benefits..... 1

3. Ordering information.....2

4. Functional diagram.....2

5. Pinning information.....4

5.1. Pinning..... 4

5.2. Pin description..... 4

6. Functional description..... 5

7. Limiting values..... 5

8. Recommended operating conditions.....5

9. Static characteristics.....6

10. Dynamic characteristics..... 7

10.1. Waveforms and test circuit..... 10

11. Package outline..... 13

12. Abbreviations..... 16

13. Revision history.....16

14. Legal information.....17

© Nexperia B.V. 2024. All rights reserved

For more information, please visit: <http://www.nexperia.com>

For sales office addresses, please send an email to: salesaddresses@nexperia.com

Date of release: 5 August 2024